Dual J-K Master-Slave Flip-Flop

The MC10135 is a dual master-slave dc coupled J-K flip-flop. Asynchro- nous set (S) and reset (R) are provided. The set and reset inputs override the clock.

A common clock is provided with separate \overline{J} - \overline{K} inputs. When the clock is static, the \overline{J} - \overline{K} inputs do not effect the output.

The output states of the flip-flop change on the positive transition of the clock.

- $P_D = 280 \text{ mW typ/pkg (No Load)}$
- $f_{Tog} = 140 \text{ MHz typ}$
- $t_{pd} = 3.0 \text{ ns typ}$
- t_r , $t_f = 2.5$ ns typ (20%–80%)

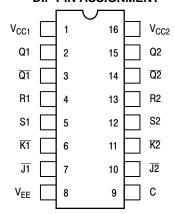
LOGIC DIAGRAM J1 Q1 R1 4 C 9 S2 12 J2 10 K2 13

Vc31 riv.1

o _2 = 1 iN 16

= PIN 8

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Pack1 For PLCC pin assignment, see the Pin Con Tables on page 18 of the ON Semiconductor Data Book (DL122/D).

R-S TRUTH TABLE

S

L

Н

L

Т

3EVICE

N.D. = Not Defined

 Q_{n+1}

 Q_n

Н

CLOCK J-K TRUTH TABLE*

J	K	Q _{n+1}
Η	L	$\overline{Q_n}$
Н	L	L
L	Н	Н
Н	Н	Q_n

*Output states change on positive transition of clock for \overline{J} - \overline{K} input condition present.



ON Semiconductor

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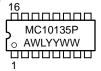
MARKING DIAGRAMS



CDIP-16 **L SUFFIX CASE 620** 16 _______ MC10135L **AWLYYWW**



PDIP-16 P SUFFIX **CASE 648**





PLCC-20 **FN SUFFIX CASE 775**



= Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping		
MC10135L	CDIP-16	25 Units / Rail		
MC10135P	PDIP-16	25 Units / Rail		
MC10135FN	PLCC-20	46 Units / Rail		

ELECTRICAL CHARACTERISTICS

			Test Limits							
		Pin Under	-30)°C		+25°C		+85	5°C	
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Current	Ι _Ε	8		75		54	68		75	mAdc
Input Current	I _{inH}	6,7,9,10,11 4,5,12,13		425 620			265 390		265 390	μAdc
	I _{inL}	4,5,6,7,9, 10,11,12,13	0.5 0.5		0.5 0.5			0.3 0.3		μAdc
Output Voltage Logic 1	V _{OH}	2 2 (3.)	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage Logic 0	V _{OL}	3 3 (3.)	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdc
Threshold Voltage Logic 1	V _{OHA}	2 2 (4.)	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdc
Threshold Voltage Logic 0	V _{OLA}	3 3 (4.)		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vdc
Switching Times (50 Ω Load) Clock Input										ns
Propagation Delay	t ₉₊₂₊ t ₉₊₂₋	2 2	1.8 1.8	5.0 5.0	1.8 1.8	3.0 3.0	4.5 4.5	1.8 1.8	4.6 4.6	
Rise Time (20 to 80%)	t ₂₊ , t ₃₊	2, 3	1.1	4.8	1.1	2.0	4.5	1.1	4.7	
Fall Time (20 to 80%)	t ₂₋ , t ₃₋	2, 3	1.1	4.8	1.1	2.0	4.5	1.1	4.7	
Set Input										ns
Propagation Delay	t ₅₊₂₊ t ₁₂₊₁₅₊ t ₅₊₃₋ t ₁₂₊₁₄₋	2 15 3 14	1.8 1.8 1.8 1.8	5.6 5.6 5.6 5.6	1.8 1.8 1.8 1.8	3.0 3.0 3.0 3.0	5.0 5.0 5.0 5.0	1.8	5.2 5.2 5.2 5.2	
Reset Input										ns
Propagation Delay	t ₄₊₂ - t ₄₊₃ - t ₁₃₊₁₅ - t ₁₃₊₁₄₊	2 3 15 14	1.8 1.8 1.8 1.8	5.6 5.6 5.6 5.6	1.8 1.8 1.8 1.8	3.0 3.0 3.0 3.0	5.0 5.0 5.0 5.0	1.8 1.8 1.8 1.8	5.2 5.2 5.2 5.2	
Setup Time	t _{setup}	7	2.5		2.5	1.0		2.5		ns
Hold Time	t _{hold}	7	1.5		1.5	1.0		2.5		ns
Toggle Frequency (Max)	f _{tog}	2	125		125	140		125		MHz

 V_{IHmax} 3. Output level to be measured after a clock pulse has been applied to the \overline{C}_{E} Input (Pin 6) V_{IHAmax} 4. Output level to be measured after a clock pulse has been applied to the $\overline{\text{C}}_{\text{E}}$ Input (Pin 6)

Individually test each input; apply V_{IHmax} to pin under test.
 Individually test each input; apply V_{ILmin} to pin under test.

ELECTRICAL CHARACTERISTICS (continued)

			TEST VOLTAGE VALUES (Volts)					
@ Test Temperature			V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
		-30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
		+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
		+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
		Pin	TEST V	OLTAGE A	PPLIED TO	PINS LISTED E	BELOW	α, ,
Characteristic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain Current	Ι _Ε	8					8	1, 16
Input Current	I _{inH}	6,7,9,10,11 4,5,12,13	Note 1. Note 1.				8 8	1, 16 1, 16
	l _{inL}	4,5,6,7,9, 10,11,12,13		Note 2. Note 2.			8 8	1, 16 1, 16
Output Voltage Logic 1	V _{OH}	2 2 (3.)	5 6				8 8	1, 16 1, 16
Output Voltage Logic 0	V _{OL}	3 3 (3.)	5 6				8 8	1, 16 1, 16
Threshold Voltage Logic 1	V _{OHA}	2 2 (4.)	6		5		8 8	1, 16 1, 16
Threshold Voltage Logic 0	V _{OLA}	3 3 (4.)	6		5		8 8	1, 16 1, 16
Switching Times (50 Ω Load) Clock Input					Pulse In	Pulse Out	–3.2 V	+2.0 V
Propagation Delay	t ₉₊₂₊ t ₉₊₂₋	2 2			9	2 2	8 8	1, 16 1, 16
Rise Time (20 to 80%)	t ₂₊ , t ₃₊	2, 3			9	2, 3	8	1, 16
Fall Time (20 to 80%)	t ₂₋ , t ₃₋	2, 3			9	2, 3	8	1, 16
Set Input Propagation Delay	t ₅₊₂₊ t ₁₂₊₁₅₊ t ₅₊₃₋ t ₁₂₊₁₄₋	2 15 3 14			5 12 5 12	2 15 3 14	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Reset Input Propagation Delay	t ₄₊₂ - t ₄₊₃ - t ₁₃₊₁₅ - t ₁₃₊₁₄₊	2 3 15 14			4 4 13 13	2 3 15 14	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Setup Time	t _{setup}	7			6, 9	2	8	1, 16
Hold Time	t _{hold}	7			6, 9	2	8	1, 16
Toggle Frequency (Max)	f _{tog}	2			9	2	8	1, 16

1.	Individually test each input; apply V _{IHmax} to pin under test.
2.	Individually test each input; apply V _{II min} to pin under test.

 	,	 ,	- ILIIIII .	 	 -	

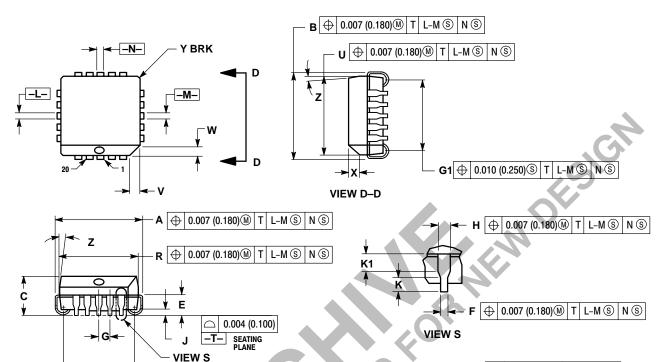
3.	Output level to be measured after a clock pulse has been applied to the \overline{C}_{E} Input (Pin 6)		V _{IHmax} V _{ILmin}
4.	Output level to be measured after a clock pulse has been applied to the \overline{C}_{E} Input (Pin 6)		V _{IHAmax}

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

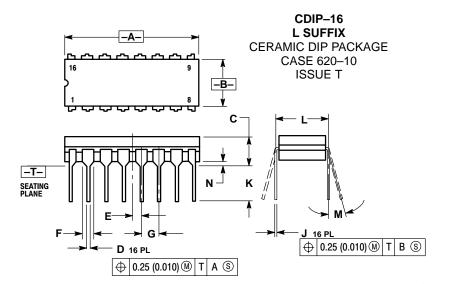
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Е	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
X	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2°	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

PACKAGE DIMENSIONS



NOTES:

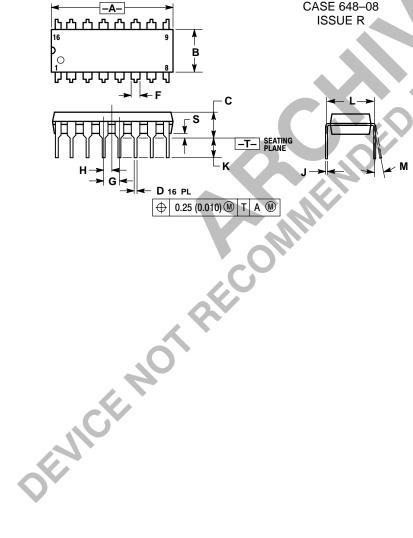
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIN	IETERS		
DIM	MIN	MAX	MIN	MAX		
Α	0.750	0.785	19.05	19.93		
В	0.240	0.295	6.10	7.49		
C		0.200		5.08		
D	0.015	0.020	0.39	0.50		
E	0.050	BSC	1.27 BSC			
F	0.055	0.065	1.40	1.65		
G	0.100	BSC	2.54 BSC			
Н	0.008	0.015	0.21	0.38		
K	0.125	0.170	3.18	4.31		
L	0.300 BSC		7.62 BSC			
M	0 °	15°	0 °	15°		
N	0.020	0.040	0.51	1.01		

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

Notes



Notes





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